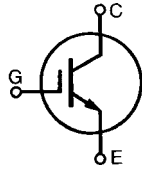


HiPerFAST™ IGBT

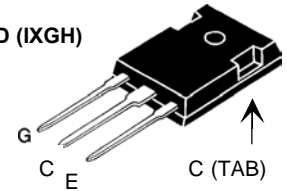
IXGH 50N60B
IXGK 50N60B
IXGT 50N60B
IXGJ 50N60B



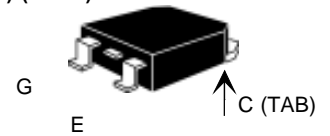
$V_{CES} = 600 \text{ V}$
 $I_{C25} = 75 \text{ A}$
 $V_{CE(sat)} = 2.3 \text{ V}$
 $t_{fi(typ)} = 120 \text{ ns}$

| Symbol | Test Conditions | Maximum Ratings | |
|---|--|-----------------------------------|-------------------|
| V_{CES} | $T_J = 25^\circ\text{C}$ to 150°C | 600 | V |
| V_{CGR} | $T_J = 25^\circ\text{C}$ to 150°C ; $R_{GE} = 1 \text{ M}\Omega$ | 600 | V |
| V_{GES} | Continuous | ± 20 | V |
| V_{GEM} | Transient | ± 30 | V |
| I_{C25} | $T_C = 25^\circ\text{C}$ | 75 | A |
| I_{C90} | $T_C = 90^\circ\text{C}$ | 50 | A |
| I_{CM} | $T_C = 25^\circ\text{C}$, 1 ms | 200 | A |
| SSOA (RBSOA) | $V_{GE} = 15 \text{ V}$, $T_{VJ} = 125^\circ\text{C}$, $R_G = 10 \Omega$ Clamped inductive load | $I_{CM} = 100$ @ $0.8 V_{CES}$ | A |
| P_C | $T_C = 25^\circ\text{C}$ | 300 | W |
| T_J | | -55 ... +150 | $^\circ\text{C}$ |
| T_{JM} | | 150 | $^\circ\text{C}$ |
| T_{stg} | | -55 ... +150 | $^\circ\text{C}$ |
| M_d | Mounting torque | TO-247AD | 1.13/10 Nm/lb.in. |
| | | TO-264 | 0.9/6 Nm/lb.in. |
| Maximum lead temperature for soldering 1.6 mm (0.062 in.) from case for 10 s | | 300 | $^\circ\text{C}$ |
| Weight | | TO-247 | 6 g |
| | | TO-264 | 10 g |
| | | TO-268 | 4 g |

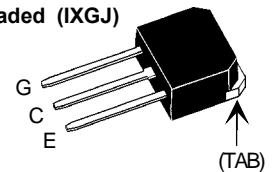
TO-247 AD (IXGH)



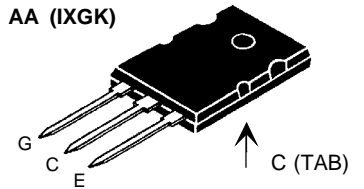
TO-268 (D3) (IXGT)



TO-268 Leaded (IXGJ)



TO-264 AA (IXGK)



G = Gate
E = Emitter
D = Drain
TAB = Collector

Features

- International standard packages
- High frequency IGBT
- Latest generation HDMOS™ process
- High current handling capability
- MOS Gate turn-on - drive simplicity

Applications

- AC motor speed control
- DC servo and robot drives
- DC choppers
- Uninterruptible power supplies (UPS)
- Switch-mode and resonant-mode power supplies

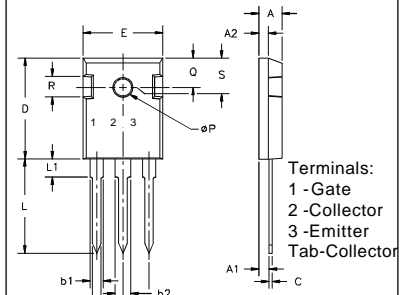
Advantages

- Easy to mount with 1 screw (insulated mounting screw hole)
- Switching speed for high frequency applications
- High power density

| Symbol | Test Conditions | Characteristic Values ($T_J = 25^\circ\text{C}$, unless otherwise specified) | | |
|---------------|--|---|------|----------------------|
| | | Min. | Typ. | Max. |
| BV_{CES} | $I_C = 250 \text{ }\mu\text{A}$, $V_{GE} = 0 \text{ V}$ | 600 | | V |
| $V_{GE(th)}$ | $I_C = 250 \text{ }\mu\text{A}$, $V_{CE} = V_{GE}$ | 2.5 | | 5.0 V |
| I_{CES} | $V_{CE} = 0.8 \cdot V_{CES}$ $V_{GE} = 0 \text{ V}$ | $T_J = 25^\circ\text{C}$ $T_J = 125^\circ\text{C}$ | 200 | μA |
| | | | 1 | mA |
| I_{GES} | $V_{CE} = 0 \text{ V}$, $V_{GE} = \pm 20 \text{ V}$ | | | $\pm 100 \text{ nA}$ |
| $V_{CE(sat)}$ | $I_C = I_{C90}$, $V_{GE} = 15 \text{ V}$ | | | 2.3 V |

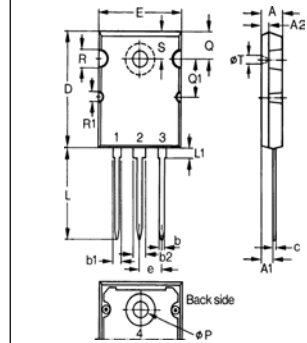
| Symbol | Test Conditions | Characteristic Values ($T_J = 25^\circ\text{C}$, unless otherwise specified) | | | |
|--------------|--|---|------|------|----|
| | | min. | typ. | max. | |
| g_{fs} | $I_C = I_{C90}$; $V_{CE} = 10\text{ V}$, Pulse test, $t \leq 300 \mu\text{s}$, duty cycle $\leq 2\%$ | 25 | 42 | S | |
| C_{ies} | $V_{CE} = 25\text{ V}$, $V_{GE} = 0\text{ V}$, $f = 1\text{ MHz}$ | | 4100 | pF | |
| C_{oes} | | | 310 | pF | |
| C_{res} | | | 95 | pF | |
| Q_G | $I_C = I_{C90}$; $V_{GE} = 15\text{ V}$, $V_{CE} = 0.5 V_{CES}$ | | 160 | nC | |
| Q_{GE} | | | 30 | nC | |
| Q_{GC} | | | 55 | nC | |
| $t_{d(on)}$ | Inductive load, $T_J = 25^\circ\text{C}$ $I_C = I_{C90}$; $V_{GE} = 15\text{ V}$ $V_{CE} = 0.8 \cdot V_{CES}$; $R_G = R_{off} = 2.7 \Omega$ Remarks: Switching times may increase for V_{CE} (Clamp) $> 0.8 \cdot V_{CES}$, higher T_J or increased R_G | | 50 | ns | |
| t_{ri} | | | 50 | ns | |
| $t_{d(off)}$ | | | 150 | 250 | ns |
| t_{fi} | | | 120 | 250 | ns |
| E_{off} | | | 3.0 | 4.5 | mJ |
| $t_{d(on)}$ | Inductive load, $T_J = 125^\circ\text{C}$ $I_C = I_{C90}$; $V_{GE} = 15\text{ V}$ $V_{CE} = 0.8 \cdot V_{CES}$; $R_G = R_{off} = 2.7 \Omega$ Remarks: Switching times may increase for V_{CE} (Clamp) $> 0.8 \cdot V_{CES}$, higher T_J or increased R_G | | 50 | ns | |
| t_{ri} | | | 50 | ns | |
| E_{on} | | | 3 | mJ | |
| $t_{d(off)}$ | | | 200 | ns | |
| t_{fi} | | | 250 | ns | |
| E_{off} | | 4.2 | mJ | | |
| R_{thJC} | | | 0.42 | KW | |
| R_{thCK} | TO-247 & TO-268 leaded packages | 0.25 | | KW | |
| | TO-264 package | 0.15 | | KW | |

TO-247 AD (IXGH) Outline



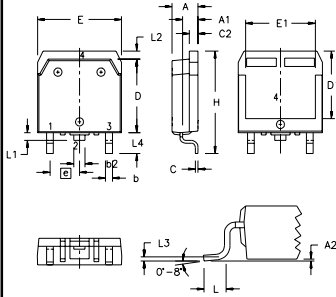
| Dim. | Millimeter | | Inches | |
|----------------|------------|-------|--------|-------|
| | Min. | Max. | Min. | Max. |
| A | 4.7 | 5.3 | .185 | .209 |
| A ₁ | 2.2 | 2.54 | .087 | .102 |
| A ₂ | 2.2 | 2.6 | .087 | .098 |
| b | 1.0 | 1.4 | .040 | .055 |
| b ₁ | 1.65 | 2.13 | .065 | .084 |
| b ₂ | 2.87 | 3.12 | .113 | .123 |
| C | .4 | .8 | .016 | .031 |
| D | 20.80 | 21.46 | .819 | .845 |
| E | 15.75 | 16.26 | .610 | .640 |
| e | 5.20 | 5.72 | 0.205 | 0.225 |
| L | 19.81 | 20.32 | .780 | .800 |
| L ₁ | | 4.50 | | .177 |
| ∅P | 3.55 | 3.65 | .140 | .144 |
| Q | 5.89 | 6.40 | 0.232 | 0.252 |
| R | 4.32 | 5.49 | .170 | .216 |
| S | 6.15 | BSC | .242 | BSC |

TO-264 AA (IXGK) Outline



| Dim. | Millimeter | | Inches | |
|----------------|------------|-------|----------|-------|
| | Min. | Max. | Min. | Max. |
| A | 4.82 | 5.13 | .190 | .202 |
| A ₁ | 2.54 | 2.89 | .100 | .114 |
| A ₂ | 2.00 | 2.10 | .079 | .083 |
| b | 1.12 | 1.42 | .044 | .056 |
| b ₁ | 2.39 | 2.69 | .094 | .106 |
| b ₂ | 2.90 | 3.09 | .114 | .122 |
| c | 0.53 | 0.83 | .021 | .033 |
| D | 25.91 | 26.16 | 1.020 | 1.030 |
| E | 19.81 | 19.96 | .780 | .786 |
| e | 5.46 BSC | | .215 BSC | |
| J | 0.00 | 0.25 | .000 | .010 |
| K | 0.00 | 0.25 | .000 | .010 |
| L | 20.32 | 20.83 | .800 | .820 |
| L ₁ | 2.29 | 2.59 | .090 | .102 |
| P | 3.17 | 3.66 | .125 | .144 |
| Q | 6.07 | 6.27 | .239 | .247 |
| Q ₁ | 8.38 | 8.69 | .330 | .342 |
| R | 3.81 | 4.32 | .150 | .170 |
| R ₁ | 1.78 | 2.29 | .070 | .090 |
| S | 6.04 | 6.30 | .238 | .248 |
| T | 1.57 | 1.83 | .062 | .072 |

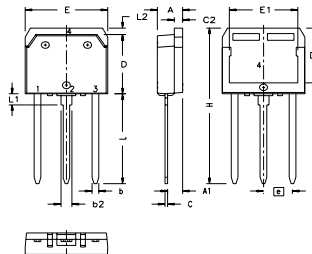
TO-268 (IXGT) Outline



| SYM | INCHES | | MILLIMETERS | |
|----------------|----------|------|-------------|-------|
| | MIN | MAX | MIN | MAX |
| A | .193 | .201 | 4.90 | 5.10 |
| A ₁ | .106 | .114 | 2.70 | 2.90 |
| A ₂ | .001 | .010 | 0.02 | 0.25 |
| b | .045 | .057 | 1.15 | 1.45 |
| b ₁ | .075 | .083 | 1.90 | 2.10 |
| C | .016 | .026 | 0.40 | 0.65 |
| C ₂ | .057 | .063 | 1.45 | 1.60 |
| D | .543 | .551 | 13.80 | 14.00 |
| D ₁ | .488 | .500 | 12.40 | 12.70 |
| E | .624 | .632 | 15.85 | 16.05 |
| E ₁ | .524 | .535 | 13.30 | 13.60 |
| e | .215 BSC | | 5.45 BSC | |
| H | .736 | .752 | 18.70 | 19.10 |
| L | .094 | .106 | 2.40 | 2.70 |
| L ₁ | .047 | .055 | 1.20 | 1.40 |
| L ₂ | .039 | .045 | 1.00 | 1.15 |
| L ₃ | .010 BSC | | 0.25 BSC | |
| L ₄ | .150 | .161 | 3.80 | 4.10 |

Terminals:
1 - Gate
2 - Collector

TO-268 (IXGJ) Leaded Outline



| SYM | INCHES | | MILLIMETERS | |
|----------------|----------|-------|-------------|-------|
| | MIN | MAX | MIN | MAX |
| A | .193 | .201 | 4.90 | 5.10 |
| A ₁ | .106 | .114 | 2.70 | 2.90 |
| b | .045 | .057 | 1.15 | 1.45 |
| b ₁ | .075 | .083 | 1.90 | 2.10 |
| C | .016 | .026 | 0.40 | 0.65 |
| C ₂ | .057 | .063 | 1.45 | 1.60 |
| D | .543 | .551 | 13.80 | 14.00 |
| D ₁ | .488 | .500 | 12.40 | 12.70 |
| E | .624 | .632 | 15.85 | 16.05 |
| E ₁ | .524 | .535 | 13.30 | 13.60 |
| e | .215 BSC | | 5.45 BSC | |
| H | 1.365 | 1.395 | 34.67 | 35.43 |
| L | .780 | .800 | 19.81 | 20.32 |
| L ₁ | .079 | .091 | 2.00 | 2.30 |
| L ₂ | .039 | .045 | 1.00 | 1.15 |

NOTE: ALL METAL AREA ARE SOLDER PLATED.

- 1 - GATE
- 2 - DRAIN (COLLECTOR)
- 3 - SOURCE (EMITTER)
- 4 - DRAIN (COLLECTOR)

IXYS reserves the right to change limits, test conditions, and dimensions.

Figure 1. Saturation Voltage Characteristics

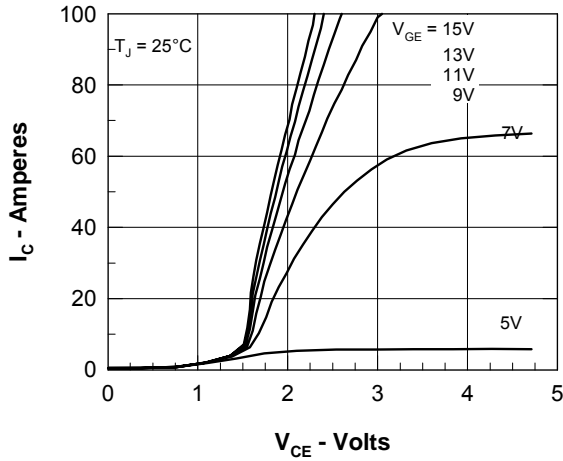


Figure 2. Extended Output Characteristics

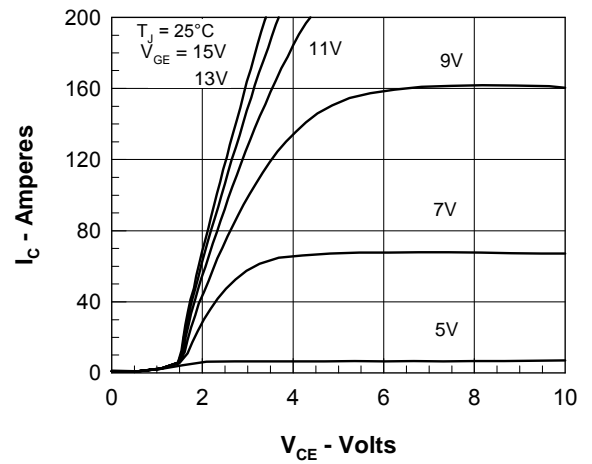


Figure 3. Saturation Voltage Characteristics

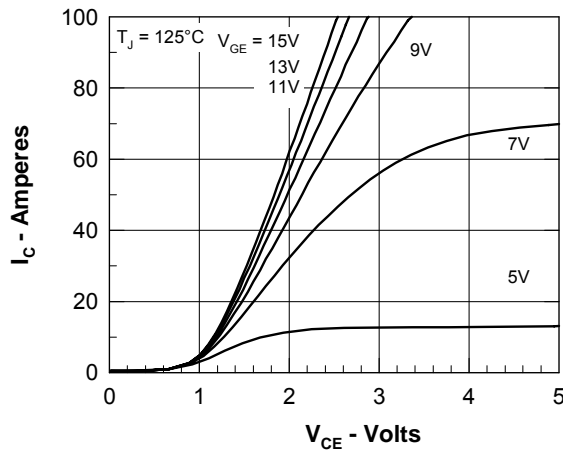


Figure 4. Temperature Dependence of $V_{CE(sat)}$

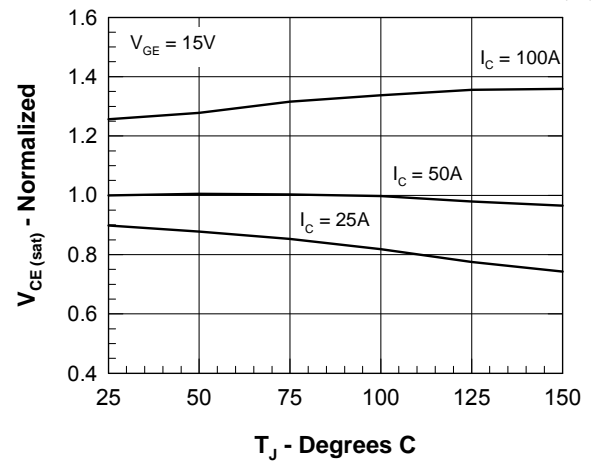


Figure 5. Admittance Curves

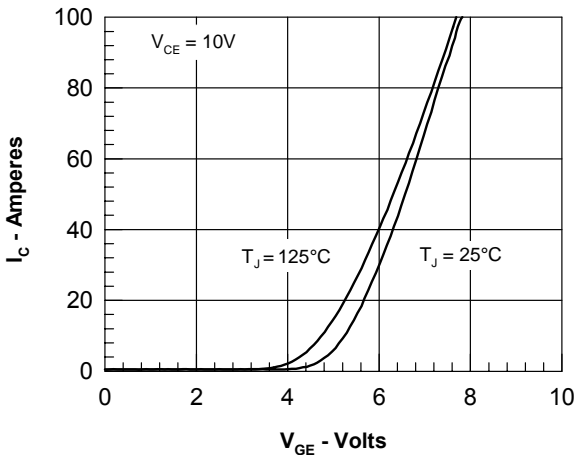


Figure 6. Capacitance Curves

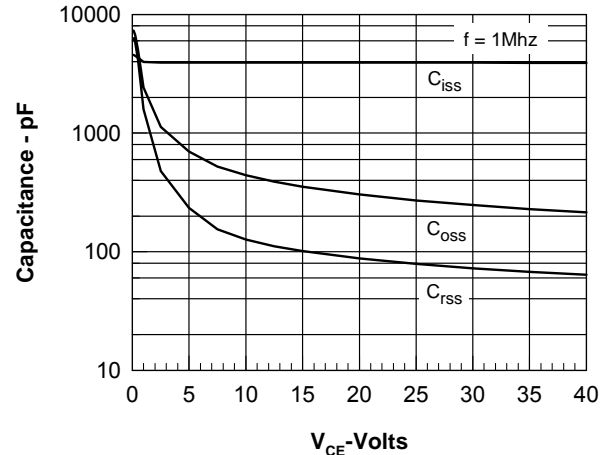


Figure 7. Dependence of E_{ON} and E_{OFF} on I_C

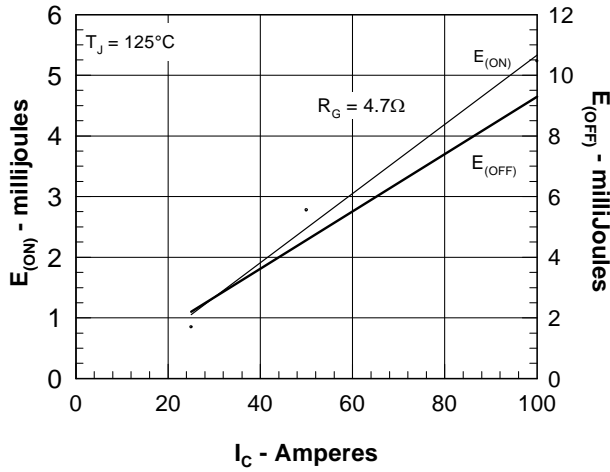


Figure 8. Dependence of E_{ON} and E_{OFF} on R_G

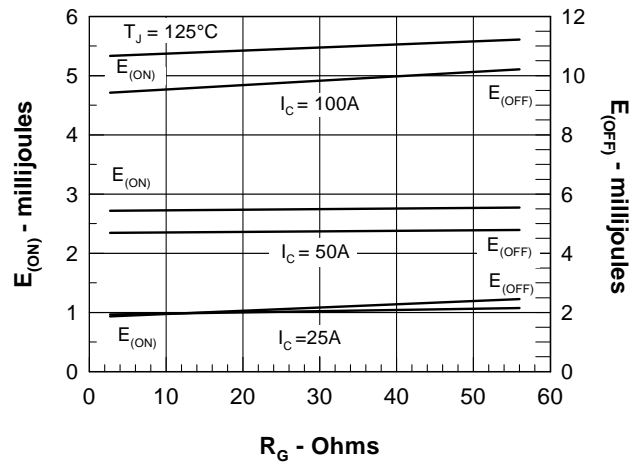


Figure 9. Gate Charge

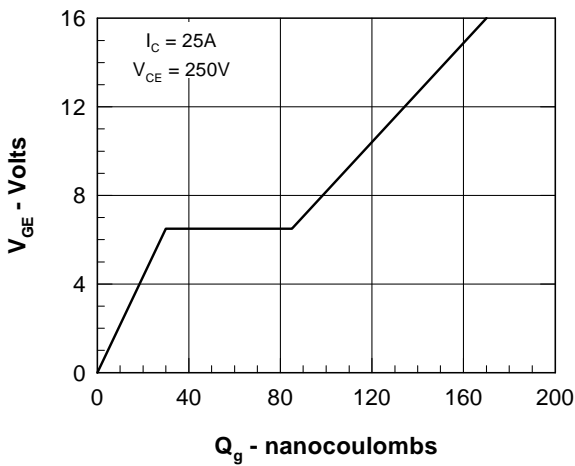


Figure 10. Turn-off Safe Operating Area

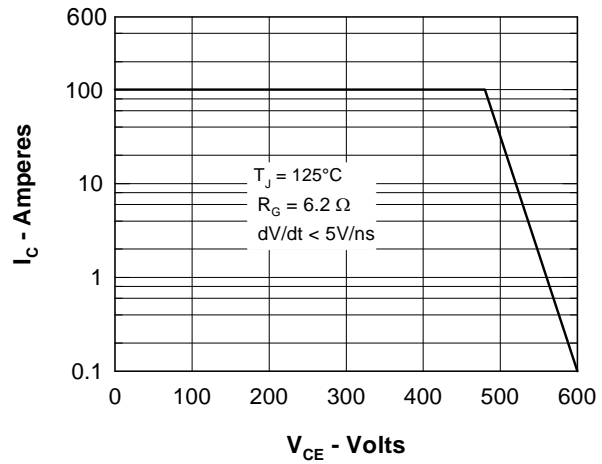
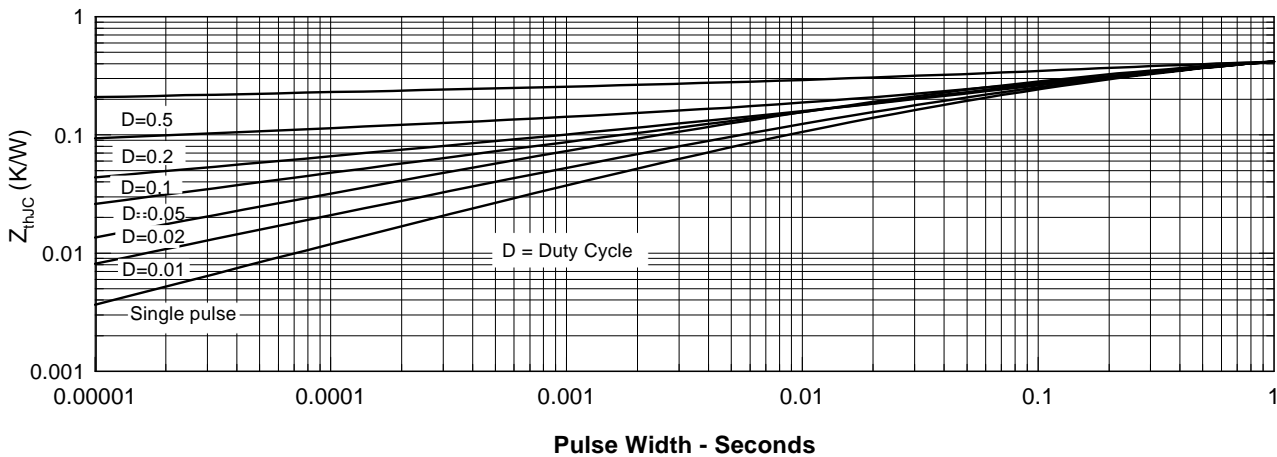


Figure 11. IGBT Transient Thermal Resistance



IXYS reserves the right to change limits, test conditions, and dimensions.

IXYS MOSFETS and IGBTs are covered by one or more of the following U.S. patents:

| | | | | | | |
|-----------|-----------|-----------|-----------|-----------|-----------|-------------|
| 4,835,592 | 4,881,106 | 5,017,508 | 5,049,961 | 5,187,117 | 5,486,715 | 6,306,728B1 |
| 4,850,072 | 4,931,844 | 5,034,796 | 5,063,307 | 5,237,481 | 5,381,025 | |